

S/N: TBA

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Proclut H
DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: St ve M. Danzig r, et al.

Serial No.: TO BE ASSIGNED
Divisional of 09/321,565

Art Unit: TO BE ASSIGNED

Filed: April 12, 2001

Examiner: TO BE ASSIGNED

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

PRELIMINARY AMENDMENT

Assistant Commissioner of
Patent and Trademarks
Washington, D.C. 20231
BOX: PATENT APPLICATIONS

Sir:

098322334-041201
This application is a divisional application of serial number
09/321, 565. After assigning a serial number to the above-
captioned application and before calculating the fee, please
undertake the following changes:

IN THE SPECIFICATION:

Please amend the specification as follows:

Please insert the following paragraph at line 3 of page 1:

1
---This application is a divisional of U.S. patent application
09/321,565 which is now U.S. Patent No. 6,221,682.---

Please replace the paragraph beginning at line 9 of page 17
with the following rewritten paragraph:

02
---In Figure 3 there is shown placement of a die (14) on a
device (22) which may optionally be either a test device or an end
use device. In either case the connections between pads (12) and